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Part Number:	**0737700100**
Status:	**Active**
Overview:	HDM® Backplane Connector System
Description:	HDM® Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 72 Circuits

Documents:

3D Model
Drawing (PDF)
Product Specification PS-73780-999 (PDF)
RoHS Certificate of Compliance (PDF)

Agency Certification

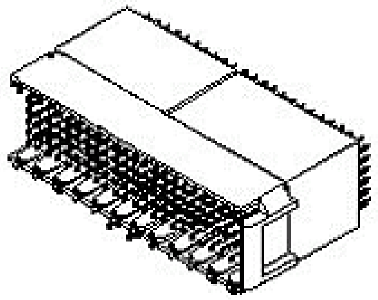
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73770
Application	Backplane, Mezzanine
Component Type	PCB Header
MolexKits	Yes
Overview	HDM® Backplane Connector System
Product Name	HDM®
UPC	800755029000

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Net Weight	13.179/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.40mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.381µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin



Series image - Reference only

EU ELV
Not Relevant

EU RoHS **China RoHS**
Compliant

REACH SVHC
Contains SVHC(2014 December 17): No

Halogen-Free Status
Low-Halogen

Need more information on product environmental compliance?

Email productcompliance@molex.com
Please visit the Contact Us section for any non-product compliance questions.

China ROHS	Green Image
ELV	Not Relevant

Search Parts in this Series
73770 Series

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | **FAQ**

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Extraction Tool	0621001000
Backplane Insertion	0621001400
Signal Contact Tool	

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	250V AC

Solder Process Data

Lead-freeProcess Capability	N/A

Material Info

Reference - Drawing Numbers

Product Specification	PS-73780-999
Sales Drawing	SD-73770-001

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